

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16070
1.3 Title of PCN	AMKOR ATJ (Japan) additional source for STM32H562x, STM32H563x and STM32H573x products in LQFP14x14 100L and LQFP20x20 144L packages.
1.4 Product Category	STM32H562x, STM32H563x and STM32H573x.
1.5 Issue date	2026-06-16

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	SCHAEFER MARC
2.1.2 Phone	+49 89460062136
2.1.3 Email	marc.schaefer@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	AMKOR ATJ (Japan)

4. Description of change

	Old	New
4.1 Description	STM32H562x, STM32H563x and STM32H573x assembly sites: - ASE Kaohsiung (Taiwan)	STM32H562x, STM32H563x and STM32H573x assembly sites: - ASE Kaohsiung (Taiwan) - current assembly - AMKOR (ATJ3) Japan - additional assembly site
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: change visible on the Marking composition.	

5. Reason / motivation for change

5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking with PP code changing - from AA : ASE KaoHsiung (Taiwan) - to 6Z: Amkor ATJ (Japan) Please refer to PCN 16070_Additional information.pdf document for further details.
-----------------	--

7. Timing / schedule

7.1 Date of qualification results	2026-09-30
7.2 Intended start of delivery	2026-10-05
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16070 RER2517 ATJ3 LQFP14x14 to 20X20 CuPd wire STM32- reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-06-16

9. Attachments (additional documentations)
16070 Public product.pdf 16070 RER2517 ATJ3 LQFP14x14 to 20X20 CuPd wire STM32- reliability plan.pdf 16070 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H562VGT6	
	STM32H562VGT6TR	
	STM32H562VIT6	
	STM32H562ZGT6	
	STM32H562ZIT6	
	STM32H563VGT6	
	STM32H563VGT6TR	
	STM32H563VIT6	
	STM32H563VIT6TR	
	STM32H563ZGT6	
	STM32H563ZGT6TR	
	STM32H563ZGT7TR	
	STM32H563ZIT6	
	STM32H573VIT6	
	STM32H573VIT6TR	
	STM32H573VIT7	
	STM32H573ZIT6	
	STM32H573ZIT6TR	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : AMKOR ATJ (Japan) additional source for STM32H562x, STM32H563x and STM32H573x products in LQFP14x14 100L and LQFP20x20 144L packages.

PCN Reference : EMBEDDED PROCESSING/26/16070

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H563VGT6TR	STM32H573ZIT6TR	STM32H563VIT7TR
STM32H562VGT7	STM32H563ZGT7	STM32H562ZGT6
STM32H562VGT6TR	STM32H563VGT6	STM32H573ZIT7
STM32H563VIT6TR	STM32H573ZIT6	STM32H563VIT7
STM32H563ZIT6	STM32H563ZGT6	STM32H573VIT7
STM32H573VIT6	STM32H563VGT7TR	STM32H563VIT6
STM32H563ZGT6TR	STM32H562VIT6	STM32H562ZIT6
STM32H562VGT6	STM32H562ZGT6TR	STM32H573VIT6TR
STM32H563ZGT7TR	STM32H562ZGT7	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.



STRIVE
FOR EXCELLENCE

MDRF-GPAM-RER2517 PCN16070 ATJ3 LQFP14x14 to 20X20 CuPd wire

Reliability Evaluation Plan

6 June 2026

MDRF GPAM Q&R

MDRF-GPAM-RER2517 PCN16070

ATJ3 LQFP14x14 to 20X20 CuPd wire

Package Test Vehicles

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process/Plant	Number of Reliability Lots	Reliability
QFP	LQFP14x14	100L	1L*484	E40/Crolles	1	Full reliability
	LQFP20x20	144L	1A*484	E40/Crolles	1	Full reliability
				E40/HHG	1	Full reliability

Qualification strategy:

- ATJ3 LQFP copper wire assembly line will be qualified with 3 package reliability lots from representative test vehicles of STM32H562x, STM32H563x and STM32H573x product lines:
 - 1 Full package reliability lot of LQFP14x14 with E40 Crolles
 - 1 Full package reliability lot of LQFP20x20 with E40 Crolles
 - 1 Full package reliability lot of LQFP20x20 with E40 HHG
- E40 Crolles/HHG technologies will be qualified in ATJ3 for LQFP14x14 and LQFP20x20 package size
- Refer to details in above and next tables.

MDRF-GPAM-RER2517 PCN16070

ATJ3 LQFP14x14 to 20X20 CuPd wire

Reliability plan

(*) tests performed after preconditioning

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Number of lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	231	3
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	3
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	3
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	77	3
HTSL	High Temperature Storage Life JESD22 A103	150°C	1000h	77	3
Construction analysis	ST internal specification JESD 22B102 JESDB100/B108	Solderability, POA, Ball shear, pull test, IMC inspection , ST internal specification	NA	50	3 (No POA and solderability for E40 HHG lot as covered by E40 Crolles lots)
ESD	ESD Charge Device Model JEDEC JS-002	500V	No failure	3	3

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice.

This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.



**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN16070
– Additional information**

Amkor ATJ (Japan) additional source for STM32H562x, STM32H563x and STM32H573x products in LQFP14x14 100L and LQFP20x20 144L packages.

MRDF – General Purpose and Automotive Microcontrollers (GPAM)

What are the changes?

Introduction of an additional assembly line to continue our path through the deployment of our Low-cost wire strategy to secure our supply chain.

Changes are described in tables below:

Table_1: for LQFP 100L 14x14 package

	Current source	Added site
Assembly site	ASE Kaohsiung (Taiwan)	Amkor ATJ (Japan)
Molding Compound ⁽²⁾	Sumitomo EME-G631SH	Sumitomo EME-G660B
Die attach Glue	HITACHI EN4900G	ABLESTIK 3230
Bonding Wire	CuPd 0.8 mils	
Leadframe	Copper Frame Spot Ag	
Leadfinishing ⁽¹⁾	Pure tin (e3)	

Table_2: for LQFP 144L 20x20 package

	Current source	Added site
Assembly site	ASE Kaohsiung (Taiwan)	Amkor ATJ (Japan)
Molding Compound ⁽²⁾	Sumitomo EME-G631SH	Sumitomo EME-G660B
Die attach Glue	HITACHI EN4900G	ABLESTIK 3230
Bonding Wire	CuPd 0.8 mils	
Leadframe	Copper Frame Spot Ag	
Leadfinishing ⁽¹⁾	Pure tin (e3)	

⁽¹⁾ Lead color and surface finishing may slightly vary depending on lead finishing.

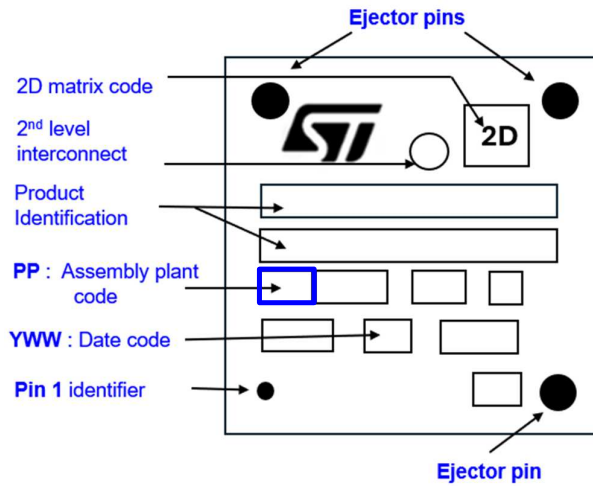
⁽²⁾ Package darkness or chromaticity may change depending on molding compound.

Pin1 identifier may change in terms of size and positioning however remaining near pin1's edge.
Marking position and size may be different upon assembly site, without any loss of information.

How can the change be seen?

The standard marking fields example below

for **LQFP 100L 14x14** package and **LQFP 144L 20x20** package

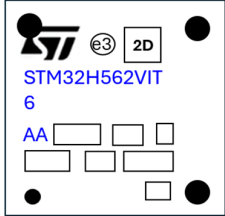
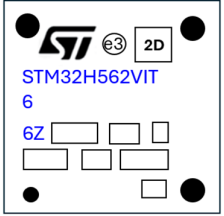
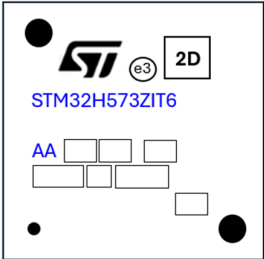
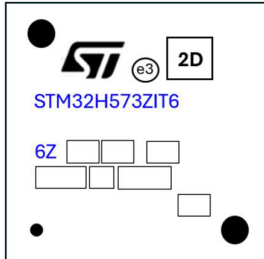


Package top view marking examples as below

Table_3: Marking fields

Marking fields		Existing	Additional
		ASE KaoHsiung (Taiwan)	Amkor ATJ (Japan)
PP	Assembly plant code	AA	6Z

Table_4: Marking examples

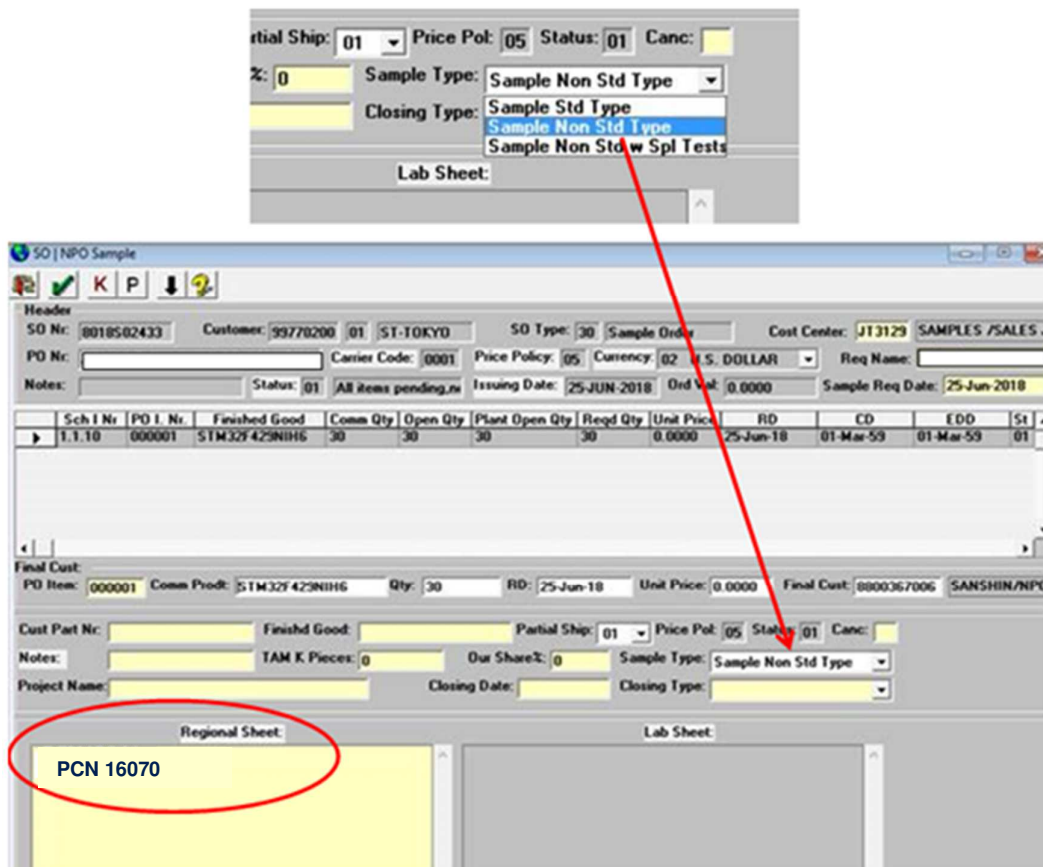
Package example	ASE KaoHsiung (Taiwan)	Amkor ATJ (Japan)
LQFP 14x14 100L (ie: STM32H562VIT6)	 Logo overlaps Ejector pin	 Logo no longer overlaps Ejector pin
LQFP 20x20 144L (ie: STM32H573ZIT6)		

Please refer to product [DataSheet](#) or Technical Note **TN1433** for package marking details.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu).
- insert the PCN number "**PCN16070**" into the NPO Electronic Sheet/**Regional Sheet**.
- request sample(s) through Notice tool, indicating a single Commercial Product for each request.



The screenshot displays the 'NPO Sample' software interface. At the top, a dropdown menu for 'Sample Type' is open, showing options: 'Sample Std Type', 'Sample Non Std Type' (highlighted), and 'Sample Non Std w Spl Tests'. A red arrow points from this menu to the 'Sample Type' field in the main form. The main form includes fields for 'SO No.', 'Customer', 'SO Type', 'Cost Center', 'PO No.', 'Carrier Code', 'Price Policy', 'Currency', 'Req Name', 'Status', 'Issuing Date', 'Ord Val', and 'Sample Req Date'. Below these is a table with columns: 'Sch I Nr', 'PO I. Nr', 'Finished Good', 'Comm Qty', 'Open Qty', 'Plant Open Qty', 'Reqd Qty', 'Unit Price', 'RD', 'CD', 'EOD', and 'St'. The table contains one row with data. Below the table, there are fields for 'Final Cust', 'PO Item', 'Comm Prod', 'Qty', 'RD', 'Unit Price', and 'Final Cust'. At the bottom, there are fields for 'Cust Part Nr', 'Finishd Good', 'Partial Ship', 'Price Pol', 'Status', 'Canc', 'Notes', 'TAM K Pieces', 'Our Share%', 'Sample Type', 'Closing Date', and 'Closing Type'. The 'Regional Sheet' tab is selected, and the text 'PCN 16070' is circled in red within this sheet.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics International NV and its affiliates (“ST”) reserve the right to make changes corrections, enhancements, modifications, and improvements to ST products and/or to this document any time without notice. This document is provided solely for the purpose of obtaining general information relating to an ST product. Accordingly, you hereby agree to make use of this document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind. You further acknowledge and agree that this document shall not be construed as an admission, acknowledgement or evidence of any kind, including, without limitation, as to the liability, fault or responsibility whatsoever of ST or any of its affiliates, or as to the accuracy or validity of the information contained herein, or concerning any alleged product issue, failure, or defect. ST does not promise that this document is accurate or error free and specifically disclaims all warranties, express or implied, as to the accuracy of the information contained herein. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this document.

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

Information furnished is believed to be accurate and reliable. However, ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein. Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously in any prior version of this document.